

**In the United States Patent and Trademark Office**

In re the application of  
Lee D. Whetsel

TI-25300.2

Div. of Serial No.: 09/745,523      Div. of Art Unit: 2829

Filed: herewith

Examiner: TBD

Title: Probeless Testing of Pad Buffers on Wafer

**Preliminary Amendment A Under 37 CFR 1.111**

March 23, 2004

Asst. Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)  
I hereby certify that the above correspondence is  
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Patents, P.O. Box 1450, Alexandria, VA 22313-1450  
on March 23, 2004.

Lawrence J. Bassuk, Reg. No. 29,043

**In the Specification:**

Page 1, before line 1, insert the following:

This application is a divisional of Application No. 09/745,523, filed December 21, 2000, allowed December 24, 2003, which was a divisional of Application No. 09/049,626, filed March 27, 1998, now US 6,199,182, which claimed priority from Provisional Application No. 60/041,729, filed March 27, 1997.